

High Speed CMOS Logic Dual 4-Stage Static Shift Register

Features

- **Maximum Frequency, Typically 60MHz**
 $C_L = 15\text{pF}$, $V_{CC} = 5\text{V}$, $T_A = 25^\circ\text{C}$
- **Positive-Edge Clocking**
- **Overriding Reset**
- **Buffered Inputs and Outputs**
- **Fanout (Over Temperature Range)**
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- **Wide Operating Temperature Range . . . -55°C to 125°C**
- **Balanced Propagation Delay and Transition Times**
- **Significant Power Reduction Compared to LSTTL Logic ICs**
- **HC Types**
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5\text{V}$

Description

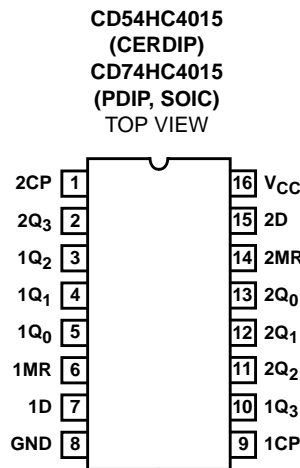
The 'HC4015 consists of two identical, independent, 4-stage serial-input/parallel-output registers. Each register has independent Clock (CP) and Reset (MR) inputs as well as a single serial Data input. "Q" outputs are available from each of the four stages on both registers. All register stages are D-type, master-slave flip-flops. The logic level present at the Data input is transferred into the first register stage and shifted over one stage at each positive-going clock transition. Resetting of all stages is accomplished by a high level on the reset line.

The device can drive up to 10 low power Schottky equivalent loads. The 'HC4015 is an enhanced version of equivalent CMOS types.

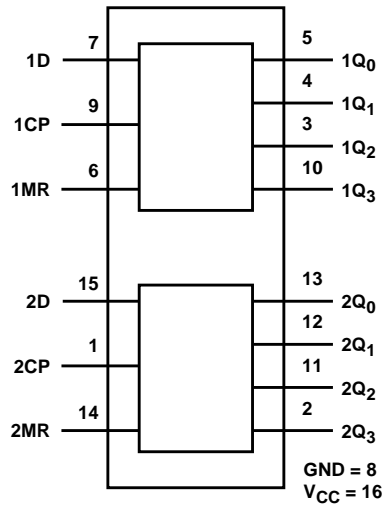
Ordering Information

PART NUMBER	TEMP. RANGE ($^\circ\text{C}$)	PACKAGE
CD54HC4015F3A	-55 to 125	16 Ld CERDIP
CD74HC4015E	-55 to 125	16 Ld PDIP
CD74HC4015M	-55 to 125	16 Ld SOIC

Pinout



Functional Diagram



TRUTH TABLE

INPUTS			OUTPUTS			
CP	D	R	Q ₀	Q ₁	Q ₂	Q ₃
↑	l	L	L	q' ₀	q' ₁	q' ₂
↑	h	L	H	q' ₀	q' ₁	q' ₂
↓	X	L	q' ₀	q' ₁	q' ₂	q' ₃
X	X	H	L	L	L	L

H = High Voltage Level

h = High Voltage Level One Set-up Time Prior to the Low to High Clock Transition

L = Low Voltage Level

l = Low Voltage Level One Set-up Time Prior to the Low to High Clock Transition

X = Don't Care.

↑ = Low to High Clock Transition

↓ = High to Low Clock Transition

q'_n = Lower case letters indicate the state of the referenced output one set-up time prior to the Low to High clock transition.

CD54HC4015, CD74HC4015

Absolute Maximum Ratings

DC Supply Voltage, V_{CC}	-0.5V to 7V
DC Input Diode Current, I_{IK}	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, I_{OK}	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, I_O	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC V_{CC} or Ground Current, I_{CC}	$\pm 50mA$

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} ($^{\circ}C/W$)
E (PDIP) Package	67
M (SOIC) Package	73
Maximum Junction Temperature	150 $^{\circ}C$
Maximum Storage Temperature Range	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s)	300 $^{\circ}C$ (SOIC - Lead Tips Only)

Operating Conditions

Temperature Range, T_A	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, V_{CC}	
HC Types2V to 6V
DC Input or Output Voltage, V_I , V_O	0V to V_{CC}
Input Rise and Fall Time	
2V	100ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25 $^{\circ}C$			-40 $^{\circ}C$ TO 85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS	
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX		
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V	
				4.5	3.15	-	-	3.15	-	3.15	-	V	
				6	4.2	-	-	4.2	-	4.2	-	V	
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V	
				4.5	-	-	1.35	-	1.35	-	1.35	V	
				6	-	-	1.8	-	1.8	-	1.8	V	
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	V_{OH}	V_{IH} or V_{IL}	-	-	-	-	-	-	-	-	-	V	
			-4	-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	V_{OL}	V_{IH} or V_{IL}	-	-	-	-	-	-	-	-	-	V	
			4	4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	± 0.1	-	± 1	-	± 1	μA	
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	8	-	80	-	160	μA	

CD54HC4015, CD74HC4015

Prerequisite for Switching Specifications

PARAMETER	SYMBOL	V _{CC} (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	MAX	MIN	MAX	MIN	MAX	
Maximum Clock Frequency	f _{MAX}	2	6	-	5	-	4	-	MHz
		4.5	30	-	24	-	20	-	MHz
		6	35	-	28	-	24	-	MHz
Clock Pulse Width	t _W	2	80	-	100	-	120	-	ns
		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns
MR Pulse Width	t _W	2	150	-	190	-	225	-	ns
		4.5	30	-	38	-	45	-	ns
		6	26	-	33	-	38	-	ns
MR Recovery Time	t _{REC}	2	50	-	65	-	75	-	ns
		4.5	10	-	13	-	15	-	ns
		6	9	-	11	-	13	-	ns
Set-up Time, Data-In to CP	t _{SUL} , t _{SUH}	2	60	-	75	-	90	-	ns
		4.5	12	-	15	-	18	-	ns
		6	10	-	13	-	15	-	ns
Hold Time, Data-In to CP	t _H	2	0	-	0	-	0	-	ns
		4.5	0	-	0	-	0	-	ns
		6	0	-	0	-	0	-	ns

Switching Specifications Input t_r, t_f = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Propagation Delay (Figure 1) Clock to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	175	-	220	-	270	ns
			4.5	-	-	35	-	44	-	54	ns
		C _L = 15pF	5	-	14	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	30	-	37	-	46	ns
MR to Q _n , (Clock High)	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	275	-	345	-	415	ns
			4.5	-	-	55	-	64	-	83	ns
		C _L = 15pF	-	-	25	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	47	-	54	-	71	ns
MR to Q _n , (Clock Low)	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	325	-	400	-	490	ns
			4.5	-	-	65	-	81	-	98	ns
		C _L = 15pF	-	-	25	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	55	-	69	-	83	ns
Output Transition Time (Figure 1)	t _{TLH} , t _{THL}	C _L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C _{IN}	C _L = 50pF	-	-	-	10	-	10	-	10	pF
Maximum Clock Frequency	f _{MAX}	C _L = 15pF	5	-	60	-	-	-	-	-	MHz
Power Dissipation Capacitance (Notes 2, 3)	C _{PD}	C _L = 15pF	5	-	43	-	-	-	-	-	pF

NOTES:

- C_{PD} is used to determine the dynamic power consumption, per shift register.
- $P_D = V_{CC}^2 f_i + \sum C_L V_{CC}^2$ where f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuit and Waveform

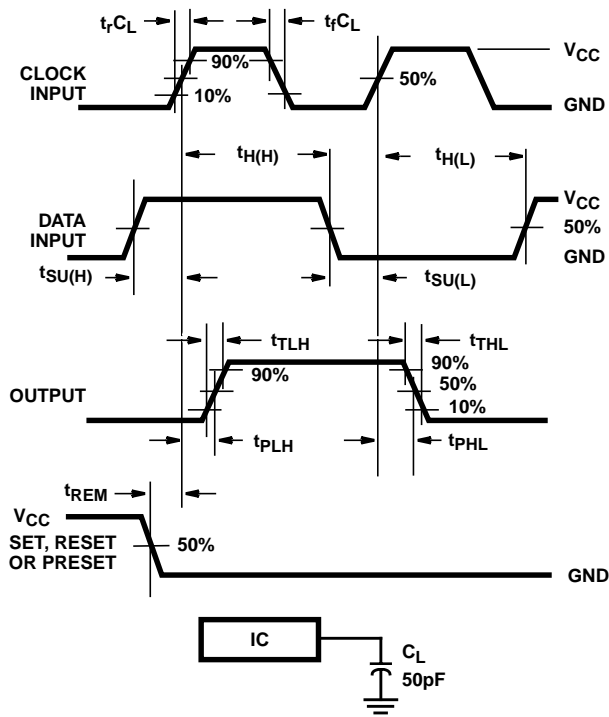


FIGURE 1. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8995301EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
CD54HC4015F3A	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type
CD74HC4015E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC4015EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC4015M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4015ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

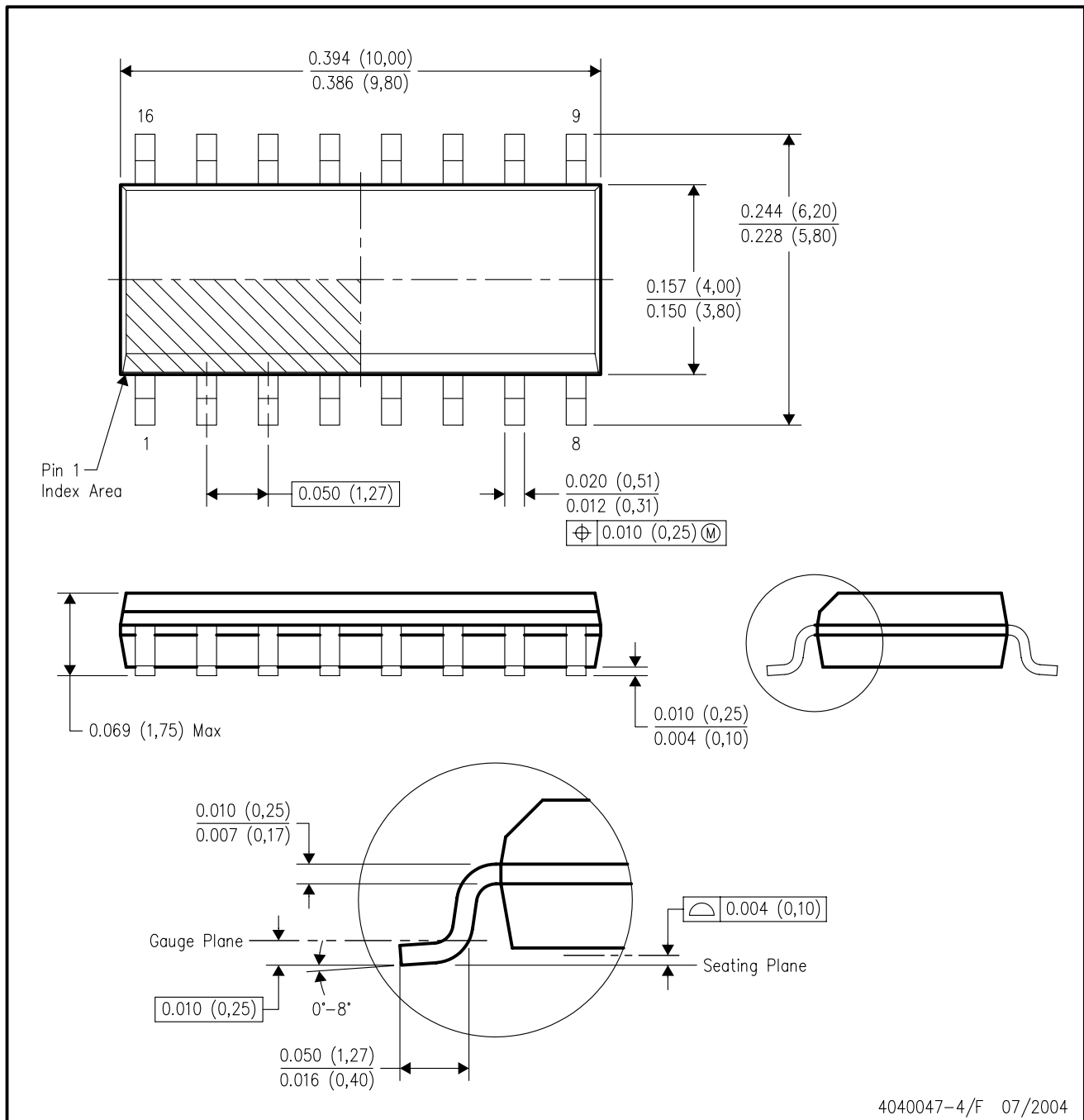
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012 variation AC.

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